

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

Listing of Claims:

Claims 1.-31. (Cancelled)

32. (Previously Presented) A substrate for mounting semiconductor devices thereon having an insulating supporting member and plural sets of wirings, and further comprising:

a semiconductor device mounting region and a resin-sealing semiconductor package region outside of said semiconductor device mounting region,

wherein said plural sets of wirings comprise a predetermined wiring pattern including wire-bonding terminals and external connection terminals,

wherein said wire bonding terminals are provided in said semiconductor package region and said external connection terminals are provided only within said semiconductor device mounting region,

wherein said substrate includes a plurality of said semiconductor device mounting regions, and

wherein said plurality of said semiconductor device mounting regions respectively have blocks of said wirings, each having a same pattern.

33. (Currently Amended) A substrate for mounting semiconductor devices thereon, having an insulating supporting member and plural sets of wirings, wherein:

said wirings form a predetermined wiring pattern including a wire bonding terminal and ~~an~~ at least one external connection terminal; and

all of said at least one external connection terminal is provided only inside of said wire bonding terminal.

34. (Previously Presented) The substrate for mounting semiconductor device thereon according to claim 33, comprising a plurality of said wiring patterns comprised of a plurality of said wirings arranged in rows and columns.

35. (Previously Presented) The substrate for mounting semiconductor devices thereon according to claim 33, wherein said wire-bonding terminal comprises a nickel layer and a gold plate layer on its surface.

36. (Currently Amended) The substrate for mounting semiconductor devices thereon according to claim 33,

wherein said external connection terminal is one of a plurality of external connection terminals, exposed on a surface of said insulating supporting member, on an opposite side to which said semiconductor device is mounted, and said external connection terminals are arranged in a grid ~~patterns~~ pattern at positions corresponding to a semiconductor device mounting region and a semiconductor package region of said substrate.

37. (Previously Presented) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for mounting the semiconductor device thereon according to claim 33 by employing a die-bonding material,

electrically connecting the semiconductor device with the wire-bonding terminals by wire-bonding,

sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and

cutting said substrate for mounting the semiconductor device thereon and said sealing resin in one operation to be separated into the individual semiconductor package.

38. (New) The substrate for mounting semiconductor devices thereon according to claim 33, wherein said external connection terminal is one of a plurality of external connection terminals, exposed on a surface of said insulating supporting member, on an opposite side to which said semiconductor device is mounted, and wherein all of said plurality of external connection terminals are located only inside of said wire bonding terminal.

39. (New) The substrate for mounting semiconductor devices thereon according to claim 38, wherein said wire bonding terminal is one of a plurality of wire bonding terminals of said substrate, and wherein said plurality of external connection terminals are positioned only within the plurality of the wire bonding terminals.

40. (New) The substrate for mounting semiconductor devices thereon according to claim 33, wherein said wire bonding terminal is one of a plurality of wire bonding terminals of said substrate, and wherein said at least one external connection terminal is positioned only inside of the plurality of wire bonding terminals.